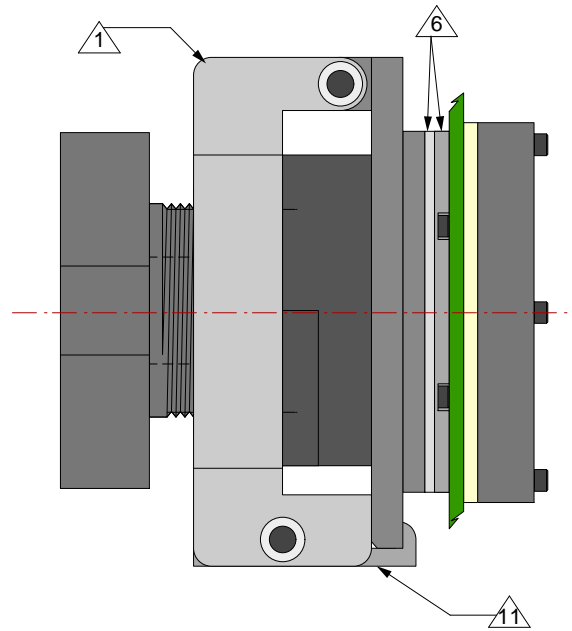


Top View

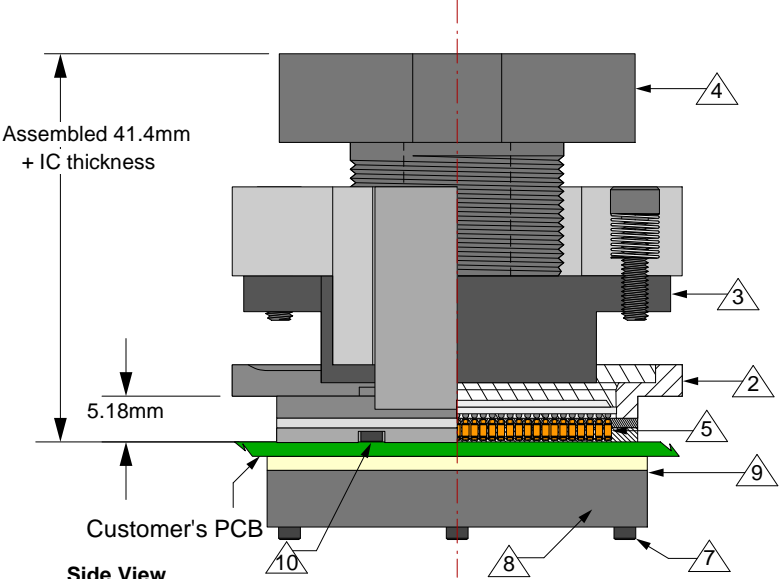


Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid


Materials:

- △1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- △2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- △3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- △4 Compression Screw: Clear anodized Aluminum. Height = 27 mm
- △5 Pogo Pin:
Plungers - Hardened Steel/ Gold plated
Barrel - Copper Alloy/ Gold plated
Spring - Stainless Steel/ Gold wire
- △6 Pogo Pin Guides: Ceramic Filled Peek.
- △7 Socket Base Screw: Socket Head Cap Screw, 2-56 Thread, 5/8" long.
- △8 Backing Plate: Black anodized Aluminum.
- △9 Insulation Plate: Ultem, 1.59mm thick.
- △10 Pogo Pin Guide Screw: Pan head phillips, 18-8 SS, 0-80 thread, 3/16" long.
- △11 Latch: Black anodized Aluminum.



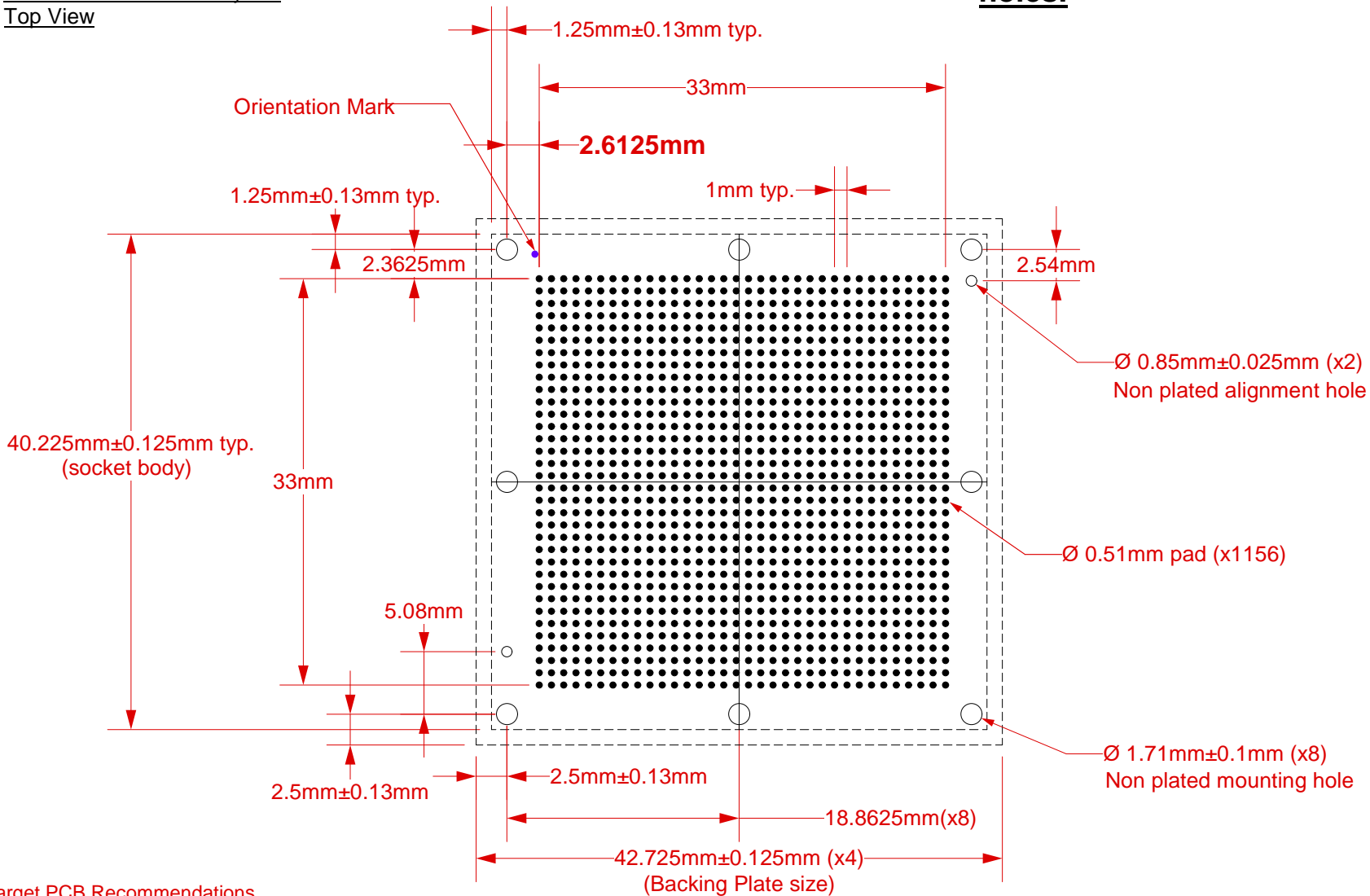
Side View
(Section AA)

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

	SS-BGA1156A-02 Drawing	Status: Released	Scale: -	Rev: A
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: E Smolentseva		Date: 02/27/09
		File: SS-BGA1156A-02 Dwg.mcd	Modified: 04/22/09	

Note: BGA pattern is shifted by 0.25mm to the right with respect to the mounting holes.

Recommended PCB Layout
Top View




Target PCB Recommendations

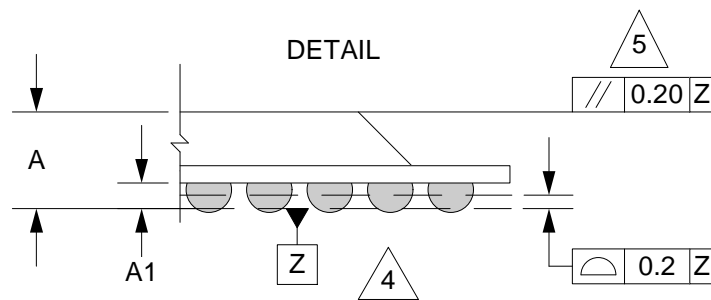
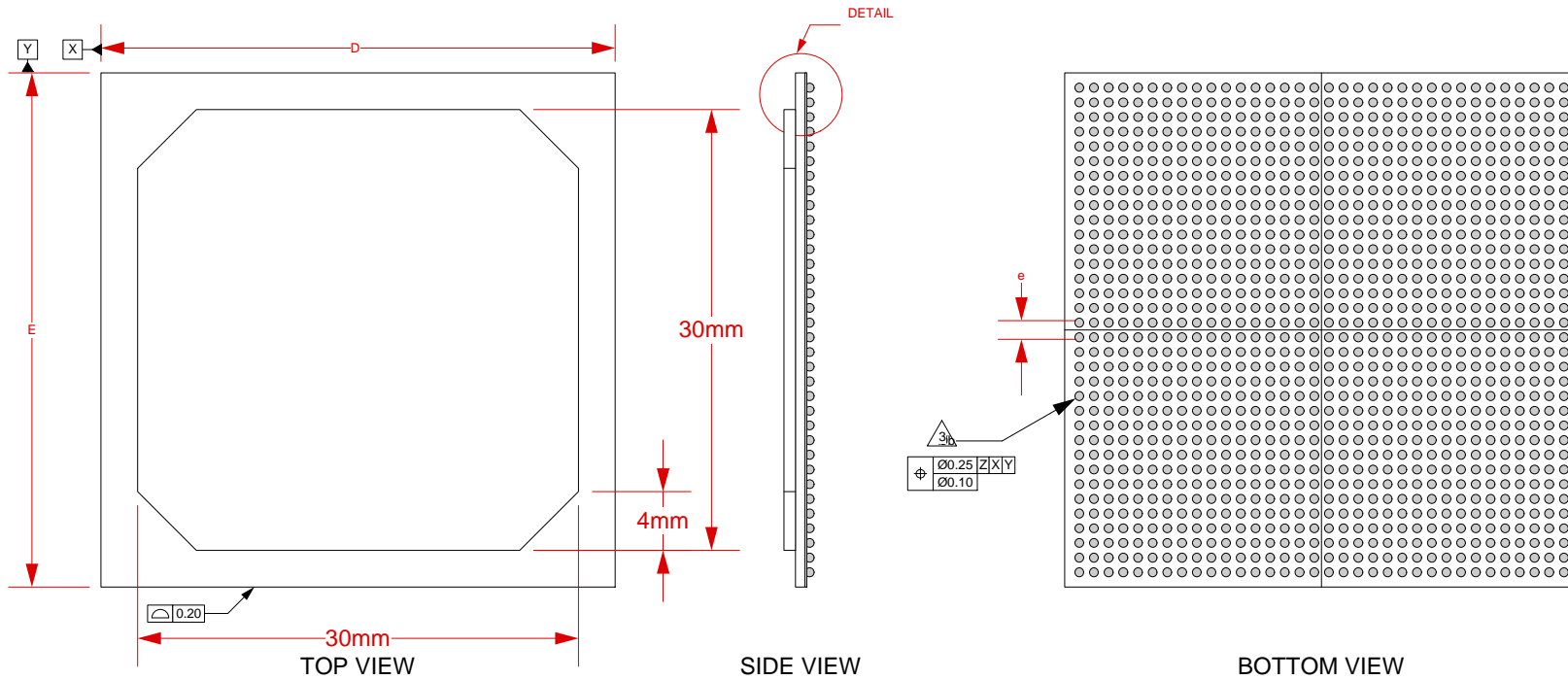
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

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		File: SS-BGA1156A-02 Dwg.mcd		Modified: 04/22/09


Compatible BGA Spec

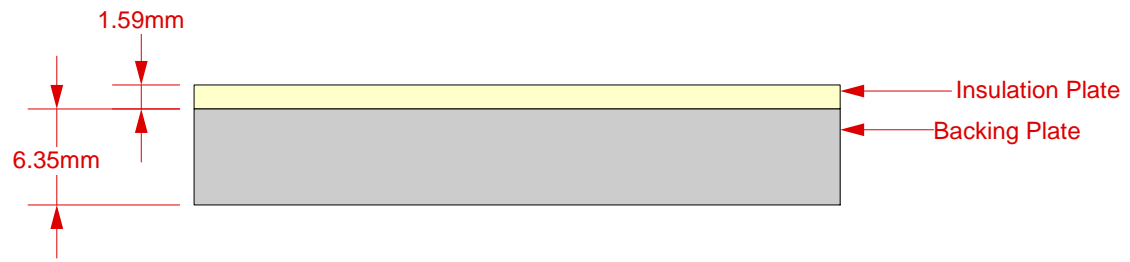
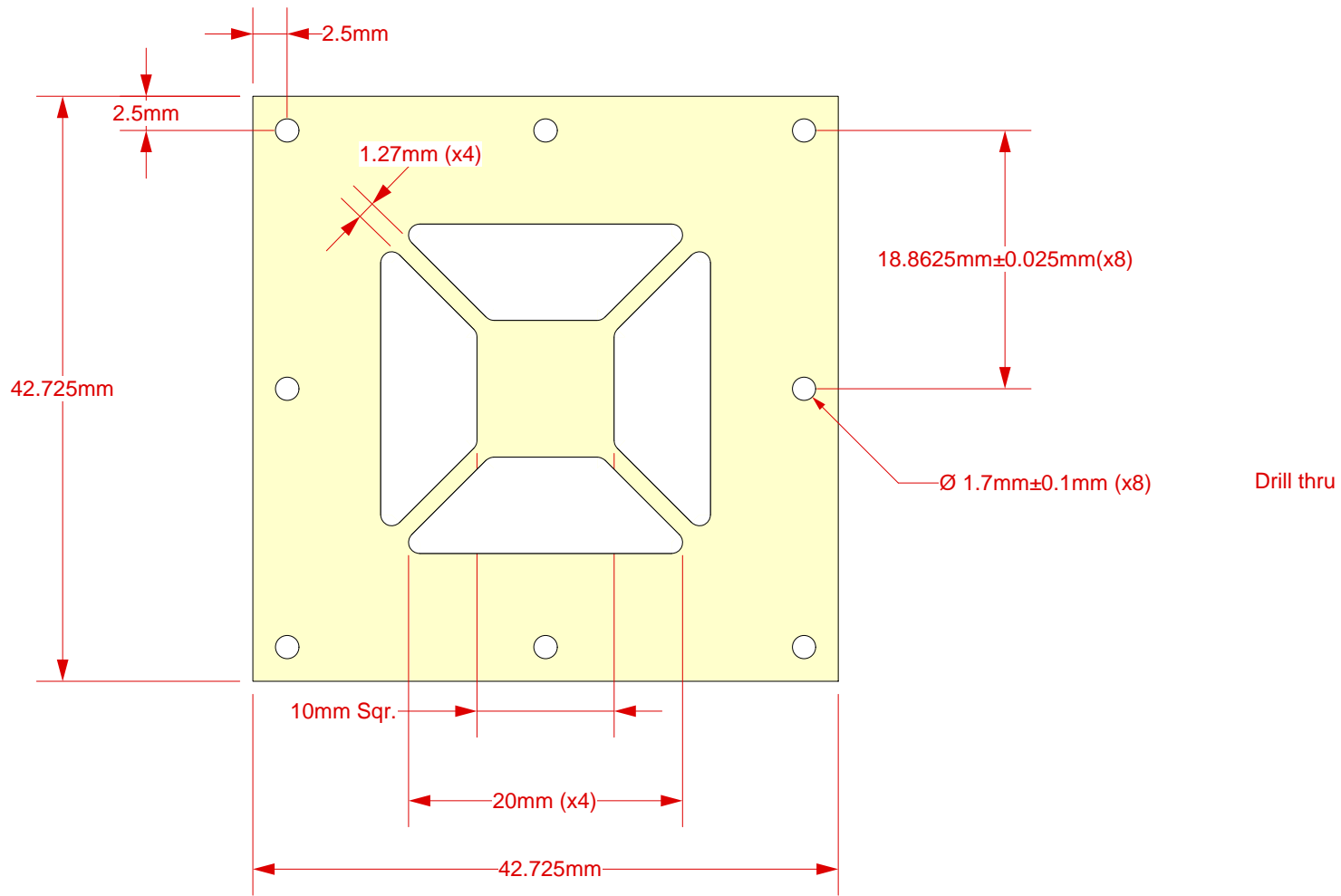


1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.23
A1	0.4	0.6
b	0.5	0.7
D	35.0 BSC	
E	35.0 BSC	
e	1.00 BSC	


Array 34x34

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		File: SS-BGA1156A-02Dwg.mcd	Modified: 04/22/09	



Side View

Description: Insulation Plate and Backing Plate

	SS-BGA1156A-02 Drawing	Status: Released	Scale: -	Rev: A
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		File: SS-BGA1156A-02 Dwg.mcd	Modified: 04/22/09	

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)